

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph on page 16, line 14, to line 18, as follows:

The present invention is suitable for use in a polishing apparatus for polishing a workpiece such as a semiconductor wafer to a flat mirror finish. Although certain preferred embodiments of the present invention have been shown and described in detail, it should be understood that various changes and modifications may be made therein without departing from the scope of the appended claims.

Please amend the paragraph on page 16, line 20, to line 23, as follows:

Industrial Applicability

~~—The present invention is suitable for use in a polishing apparatus for polishing a workpiece such as a semiconductor wafer to a flat mirror finish.~~